

FB100 Plasma Chemical Processes

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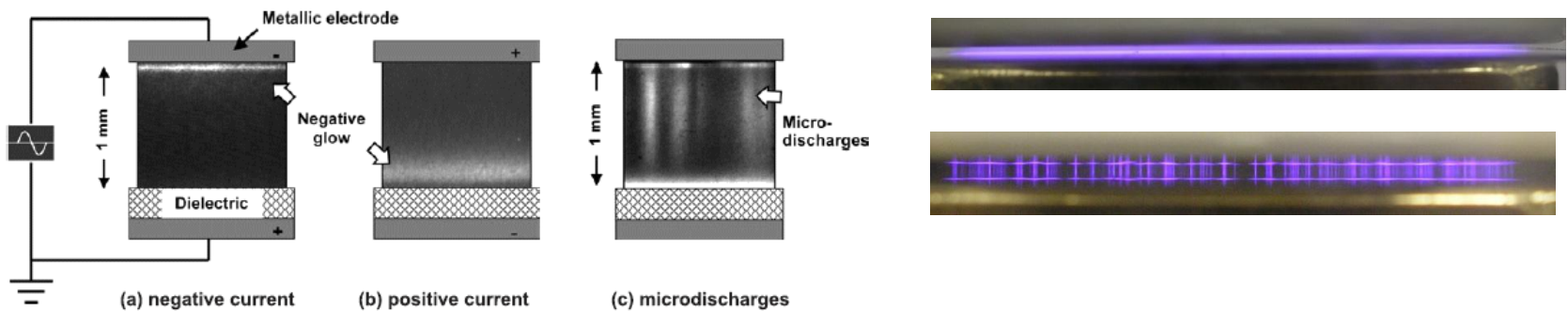
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PECVD at atmospheric pressure

- Plasma enhanced chemical vapor deposition with various sources
- Operation at 100 kPa without a vacuum system
- Plasma arcs, jets and torches – mostly operated in floating catalyst regime, most often used with microwave sources
- Atmospheric pressure glow discharge (APGD) diffusion form of dielectric barrier discharge (DBD) – deposition on substrates with heated electrode

Atmospheric pressure glow discharge

- Discharge configuration when one or both electrodes are covered with dielectric barrier (used for ozone production since 19th century)
- Filamentary DBD can be made diffusive with addition of He or Ne, which are both expensive gases, it can be also made homogeneous in Ar with certain hydrocarbons, N₂ or ammonia addition or special electrode structure.
- It was shown that during the current increase the discharge transits from a non-self-sustained discharge to a Townsend discharge and then to a subnormal glow discharge in He and Ar/NH₃ and, therefore, can be called atmospheric pressure glow discharge (APGD).
- APGD has only 1 broad current pulse in each half period while DBD has many nanosecond current pulses, non-thermal plasma at atmospheric pressure



CNTs growth in APGD

First CNTs growth published by T. Nozaki, Y. Kimura and K. Okazaki,
 J. Phys. D: Appl. Phys. 35 (2002) 2779–2784

Quartz substrate with 20 nm metal plated Ni, pretreatment in H₂ for 30 min at 600 °C
 Operation in kHz mode resulted in deposition of many defective structures

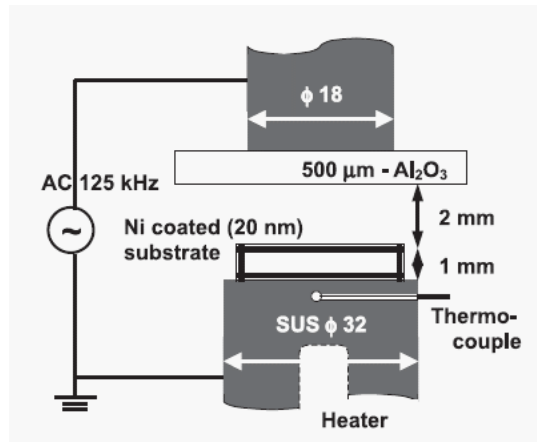


Figure 3. Electrode configuration.

Table 1. Growth parameters.

Growth temperature (°C)	400, 500, 600
Growth time (min)	5–30
H ₂ /CH ₄ ration (-)	0, 5, 10
Flow rate of gas mixture (scc min ⁻¹)	APG: He : H ₂ : CH ₄ = 900 : 100 : 0–20 DBD: He : H ₂ : CH ₄ = 150 : 150 : 15
Pressure (Torr)	760
Power (current peak)	~4 W cm ⁻² (~15 mA cm ⁻²)

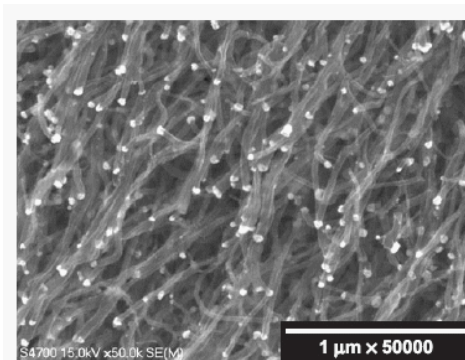
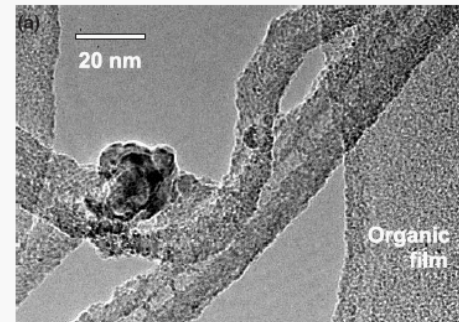
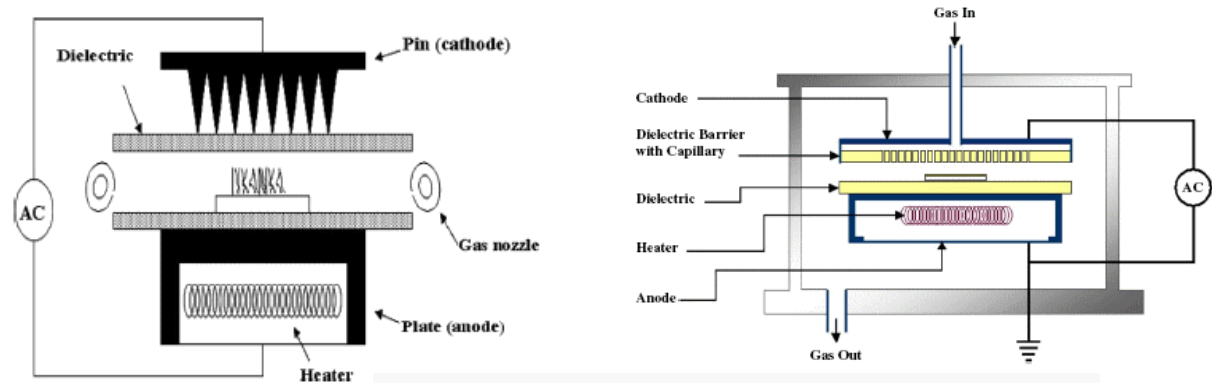


Figure 6. CNTs with uniform diameter of 40–50 nm and number density of 10⁹–10¹⁰ cm⁻² obtained after 30 min deposition.

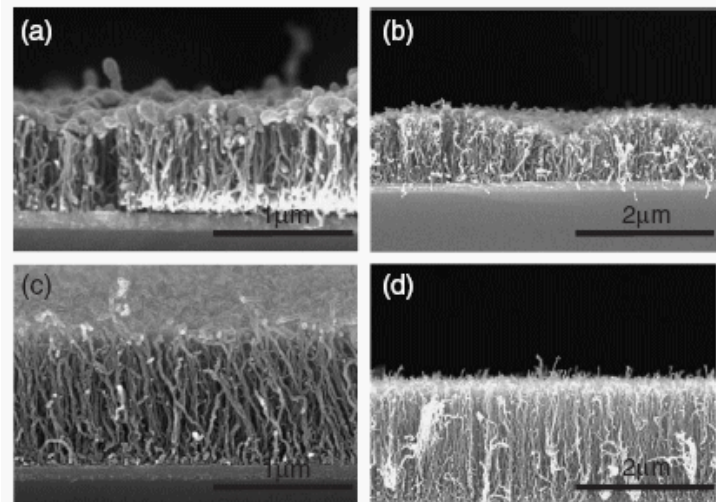


CNTs growth in APGD

- APG was also successfully used with modified electrode (pin to plate) by Y.-H. Lee, S.-H. Kyung, C.-W. Kim, G.-Y. Yeom. Carbon 44, 799 (2006) and capillary type by S.-J. Kyung, Y.-H. Lee, C.-W. Kim, J.-H. Lee, G.-Y. Yeom. Thin Solid Films 506–507, 268 (2006).



Ni (5 nm)/Cr (100 nm)/Si substrates
 He(6 slm)/NH₃(90 sccm) plasma
 with pretreatment at 400 °C for 5 min
 He/C₂H₂(60 sccm) plasma
 He/N₂(60 sccm)/C₂H₂ plasma
 He/NH₃/C₂H₂ plasma
 He/NH₃/C₂H₂ with dc bias 1.2 kV



CNTs growth in APGD

- In 2006 T. Nozaki et al. J. Appl.Phys. 99, 024310 used radio-frequency power source for CNTs growth
- APRFD creates stable continuous regime for CNTs growth, much lower operating voltage due to ion “trapping” between the electrodes, no dielectric barrier needed

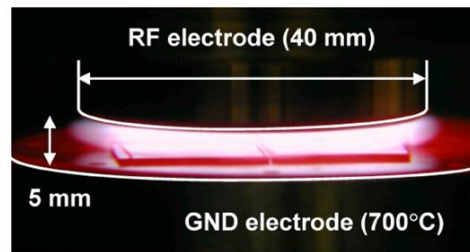
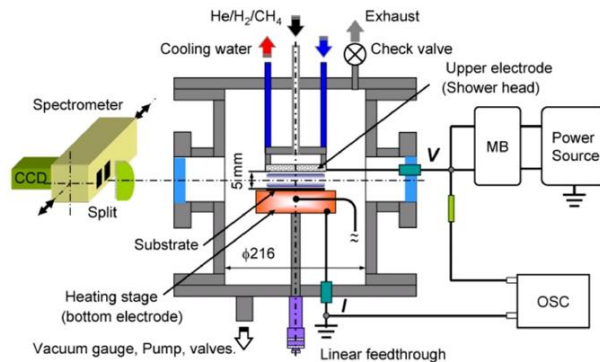
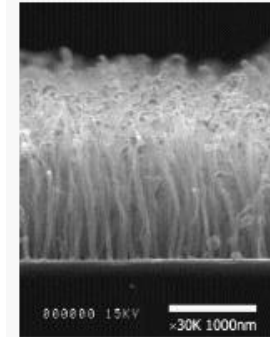
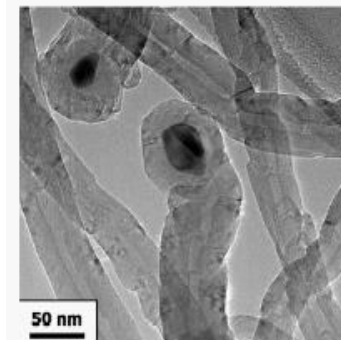


Figure 1. APRFD reactor and image of APRFD during CNT growth.



(a)

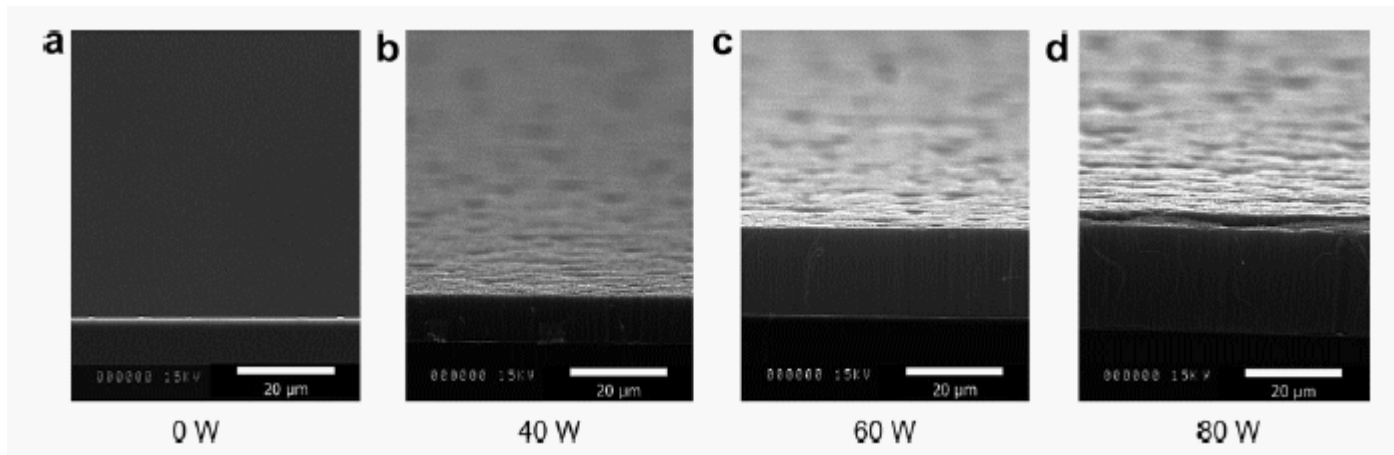


(b)

Parameters: 2 inch Si wafer <100> coated with Cr/Ni (20 nm/20 nm(sputtered)), Discharge area: 12.6 cm² Deposition time: 5, 10 , 20 min, He/H₂/C₂H₂ (1000/4-10/2 sccm)

CNTs growth in APGD

- Even with use of APRFD the growth of SWCNTs remained a challenge, key issue was the form of the catalyst
- In 2007 T. Nozaki, K. Ohnishi, K. Okazaki, U. Kortshagen. Carbon 45, 364 used densely mono-dispersed Fe–Co catalysts of a few nanometers size (first used by Maruyama) for aligned layers of SWCNTs
- Prepared nanoparticles were reduced in He/H₂ 1500/10 sccm at APRFD at 400 °C for 5 min, then 15 min at 700°C, deposition He/H₂/CH₄ 1000/30/16 sccm for 5 min at 700 °C



CNTs growth in APGD

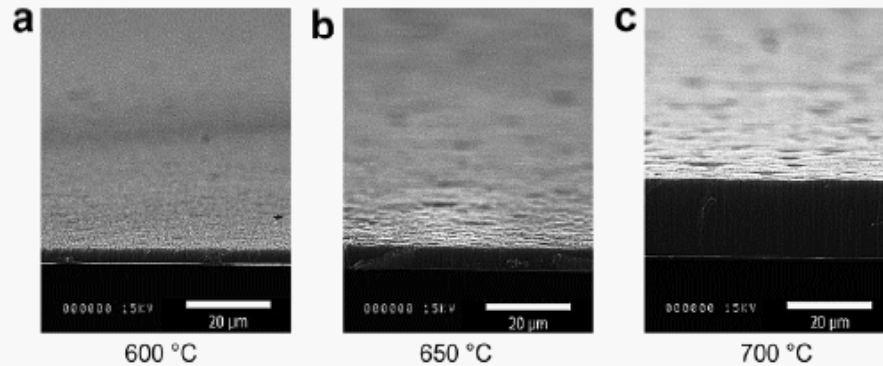


Fig. 8. SEM micrographs of SWCNTs at different substrate temperatures.

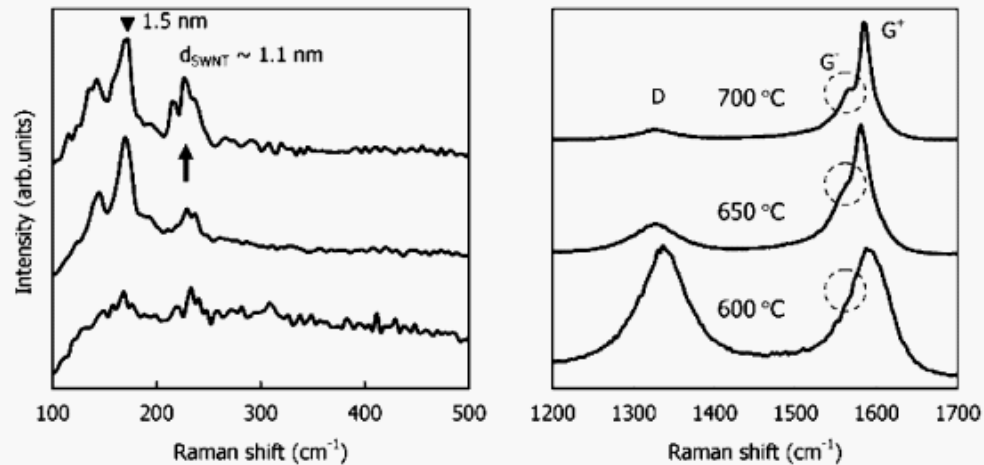


Fig. 9. Raman scattering spectra of samples shown in Fig. 8.

T. Nozaki, K. Okazaki, Carbon Nanotube Synthesis in Atmospheric Pressure Glow Discharge: A Review, *Plasma Process. Polym.* 2008, 5, 300–321

CNTs growth in APGD

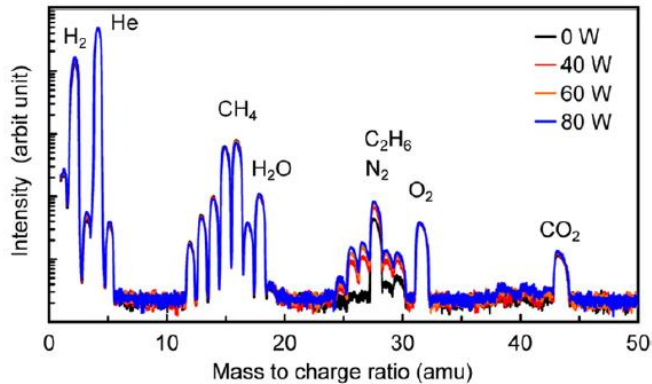


Figure 4. Mass spectrum of the reacting gas obtained directly from the sheath; conditions: He/CH₄/H₂ = 1000/16/30 cm³ min⁻¹ and 700 °C.

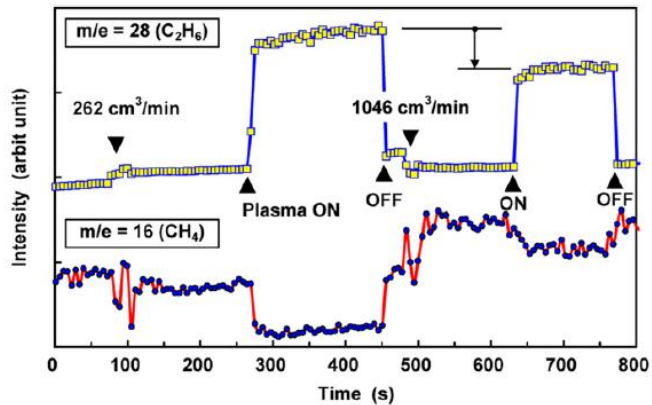


Figure 5. Time-dependent change-of-mass spectrum for $m/e = 16$ and 28. See figure 4 caption for the conditions.

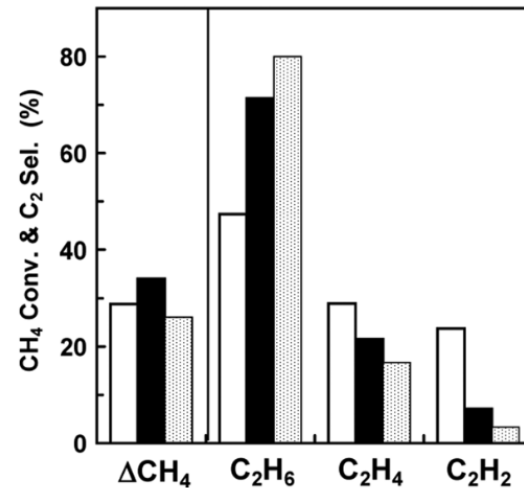


Figure 6. CH₄ conversion and selectivity for the C₂ hydrocarbon: □ 20 kPa, H₂ = 0; ■ 100 kPa, H₂ = 0; ▨ 100 kPa, H₂ = 90 cm³ min⁻¹; conditions: He/CH₄ = 3000/48 cm³ min⁻¹ and 60 W.

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T. Nozaki, S. Yoshida, T. Karatsu and K. Okazaki, Atmospheric-pressure plasma synthesis of carbon nanotubes, *J. Phys. D: Appl. Phys.* 44 (2011) 174007 (9pp).

CNTs growth in APGD in Ar/H₂/C₂H₂

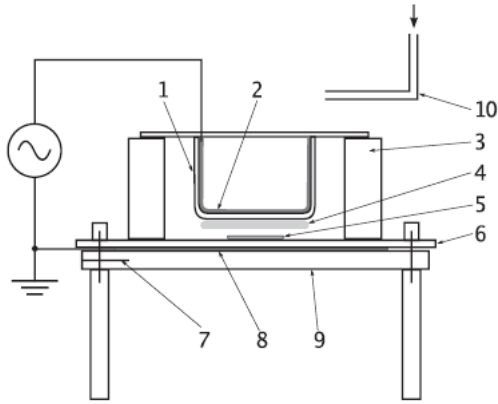


FIG. 1. Electrode configuration. 1—Simax glass dielectric, 2—upper electrode, 3—distance pillar, 4—discharge, 5—substrate, 6—AlN dielectric, 7—thermocouple, 8—bottom electrode, 9—heater, 10—gas inlet.

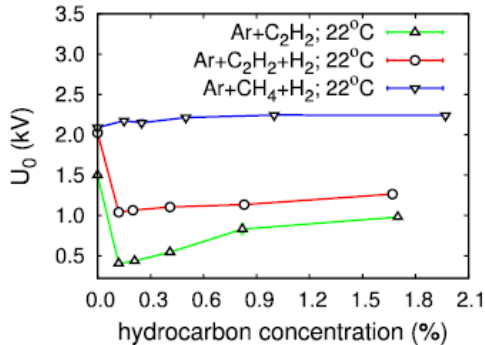


FIG. 2. The dependence of ignition voltage U_0 on the concentration of acetylene or methane added to Ar or Ar/H₂. The discharge was operated at room temperature 22°C. Argon and hydrogen flow rates were 7 slm and 100 sccm, respectively.

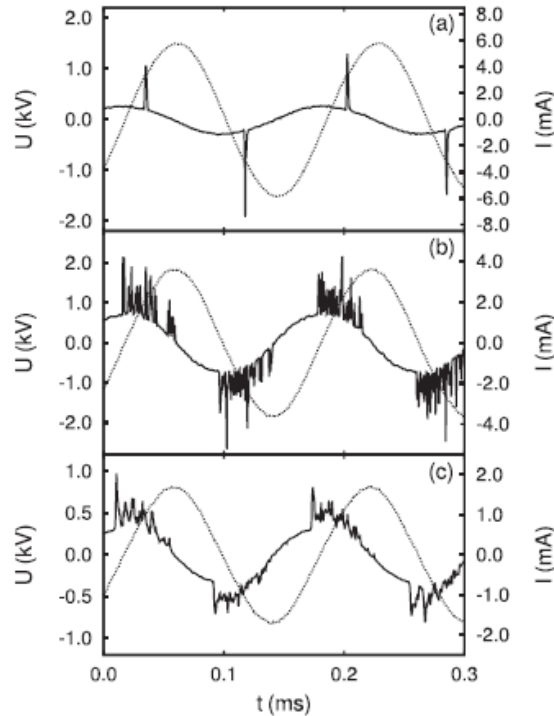


FIG. 3. The time dependence of applied voltage (dotted line) and discharge current (full line) at room temperature for (a) DBD in pure Ar, (b) DBD in Ar/CH₄, and (c) APGD in Ar/C₂H₂. The concentration of CH₄ or C₂H₂ in Ar was 0.41 vol.%. Discharges were operated slightly above the ignition voltage in particular gas mixture.

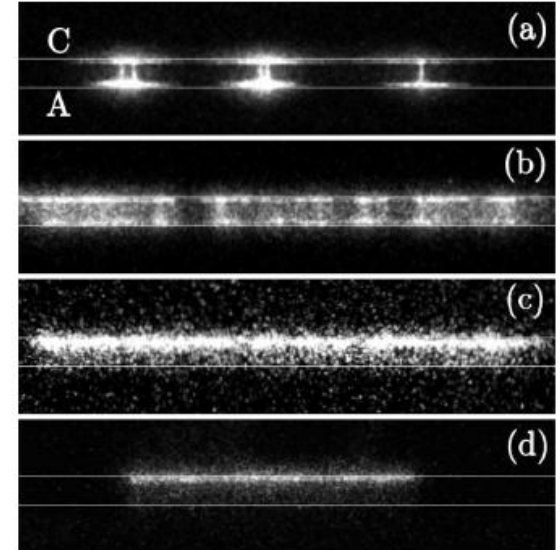


FIG. 5. ICCD images of discharges at room temperature with 80 μs (one half-period) exposure time: (a) filamentary DBD in Ar, (b) filamentary DBD in Ar/CH₄, (c) APGD in Ar/C₂H₂, and (d) APGD in Ar/C₂H₂/H₂. The concentration of CH₄ or C₂H₂ was 0.41 vol.%. Horizontal lines indicate the dielectric surfaces and the upper electrode is the instantaneous cathode in all images.

6,8 kHz power supply with 0.8–4.0 kV (peak-to-peak) voltage, electrode distance of 1,75 mm, 10x15 mm Si/SiO₂ (300 nm)/5 nm Fe catalytic layer. Ar/H₂/CH₄ or C₂H₂ mixture.

Eliáš M., Kloc P., Jašek O., Mazánková V., Trunec D., Hrdý R., Zajíčková L., Atmospheric pressure barrier discharge at high temperature: Diagnostics and carbon nanotubes deposition, *Journal of Applied Physics* 117(10) (2015) 103301.

CNTs growth in APG in Ar/H₂/C₂H₂ – diagnostics at high temperature

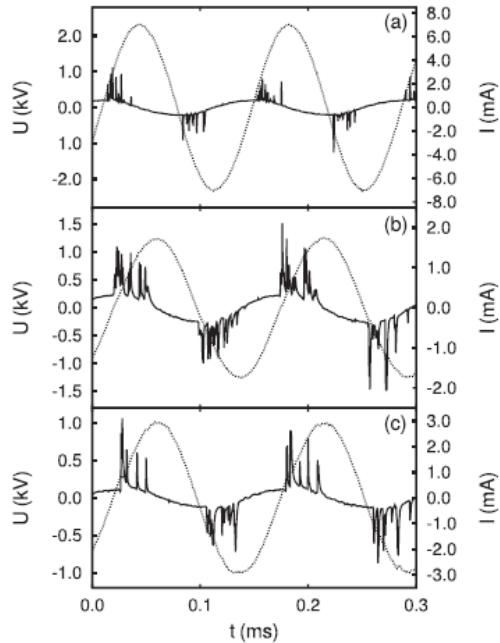


FIG. 4. The time dependence of applied voltage (dotted line) and discharge current (full line) for (a) DBD in Ar/CH₄/H₂ at 22 °C, (b) APGD Ar/C₂H₂/H₂ at 22 °C, and (c) APGD Ar/C₂H₂/H₂ at 680 °C. The concentration of CH₄ or C₂H₂ in Ar/H₂ was 0.41 vol. %. Discharges were operated slightly above the ignition voltage in particular gas mixture.

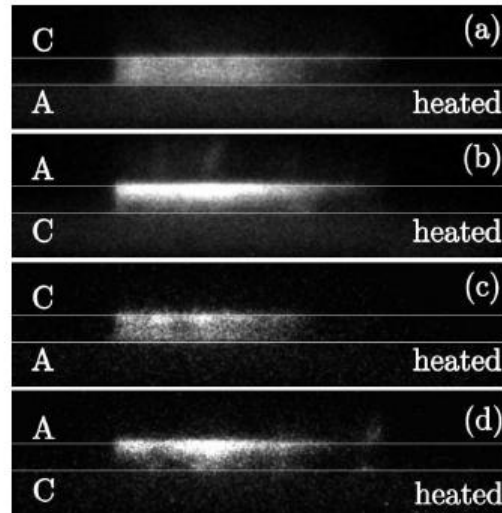


FIG. 8. ICCD images of APGD in Ar/C₂H₂/H₂ with 0.41 vol. % admixture of C₂H₂ and bottom electrode heated to 680 °C: (a) 80 μs (one half-period), instantaneous cathode at upper electrode, (b) 80 μs (one half-period), cathode at bottom electrode, (c) 5 μs, cathode at upper electrode, and (d) 5 μs, cathode at bottom electrode. Horizontal lines indicate the dielectric surfaces.

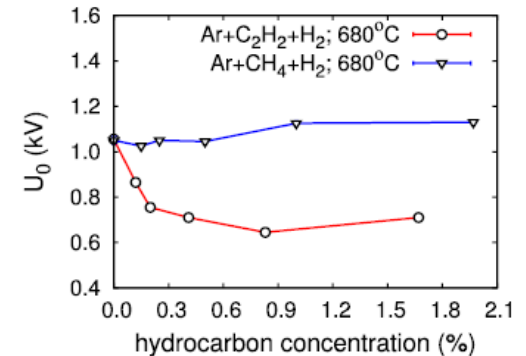


FIG. 7. The ignition voltage U_0 in dependence on the concentration of acetylene or methane added to Ar/H₂ for the temperature of bottom electrode 680 °C. Argon and hydrogen flow rates were 7 slm and 100 sccm, respectively.

If the bottom electrode was heated up to 680 °C the ignition voltage decreases due to the decrease of neutral gas concentration. Substrate temperature is 40 °C lower than heated electrode and upper electrode temperature is 250 °C lower. Due to the temperature profile the behaviour in instantaneous cathode or anode is different in each half period.

CNTs growth in APG in Ar/H₂/C₂H₂

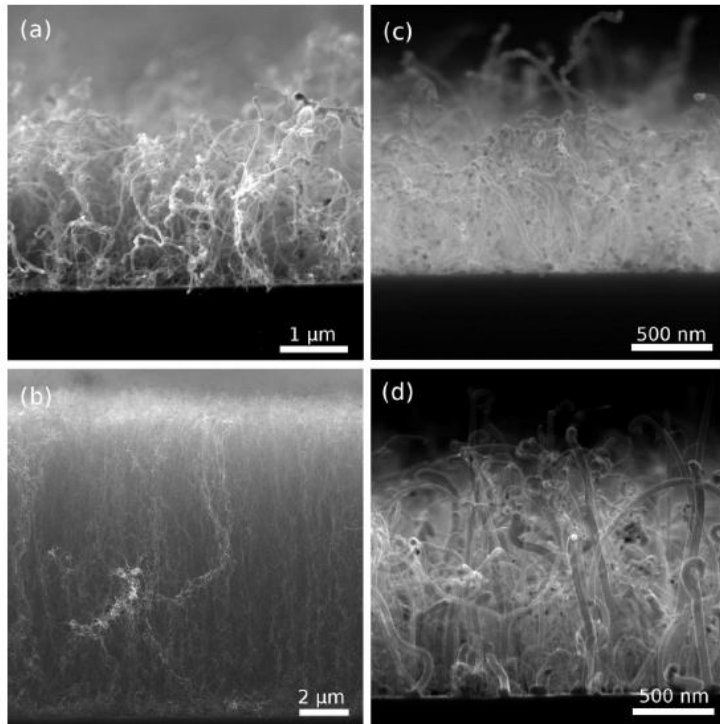


FIG. 13. Cross sectional SEM micrographs of deposited carbon nanostructures for (a) 0.1%, (b) 0.2% of C₂H₂ in Ar/C₂H₂/H₂ APG discharges, and (c) 0.2%, (d) 0.4% of CH₄ in Ar/CH₄/H₂ DBD discharges. The substrate temperature was 710 °C. The micrographs were made using TESCAN LYRA microscope.

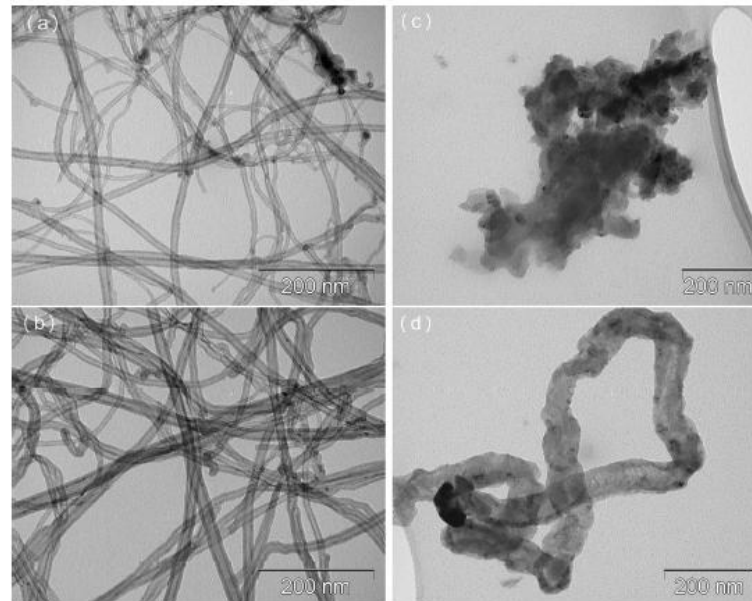
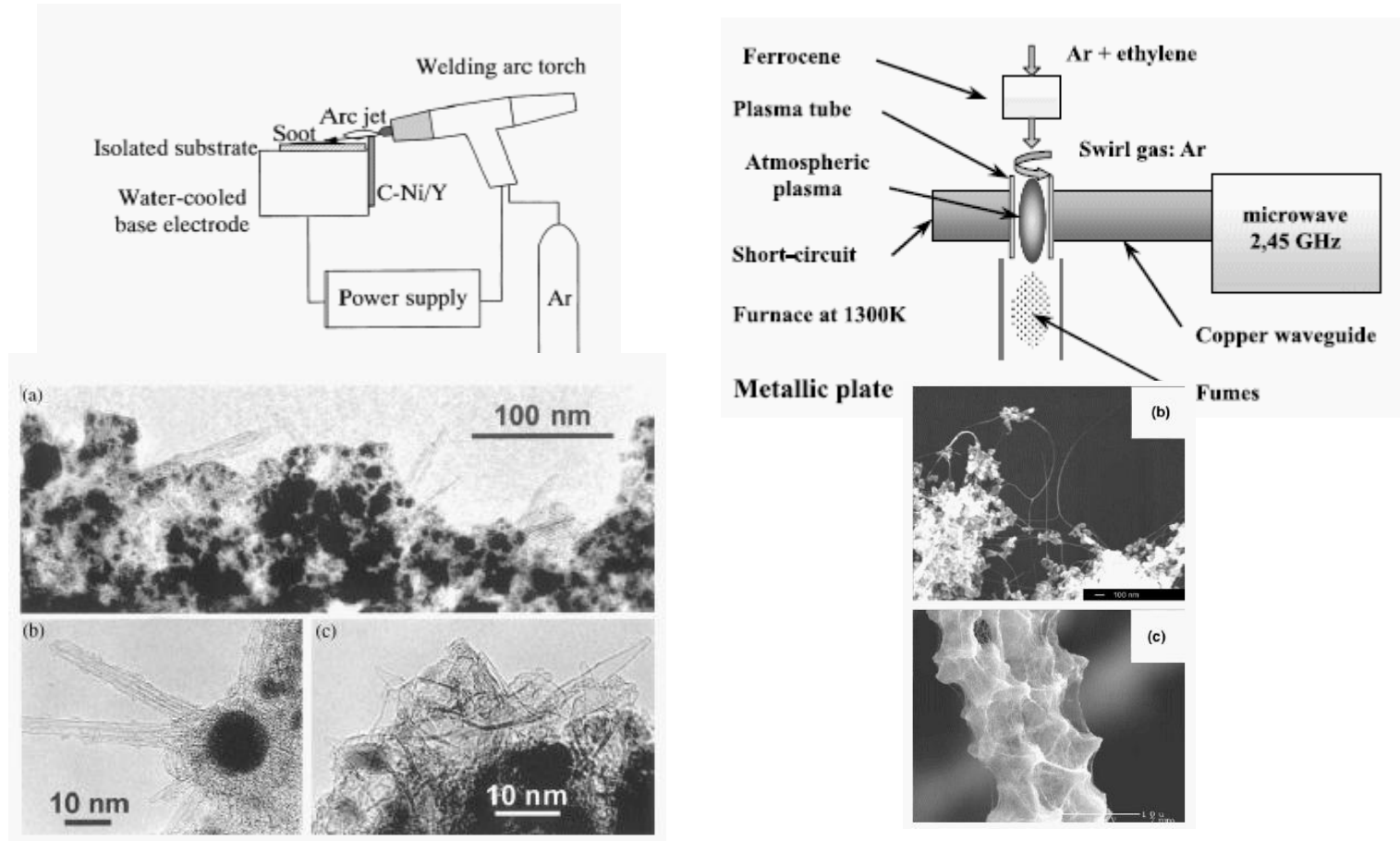


FIG. 12. TEM micrograph of the carbon nanostructures deposited from (a), (b) 0.2% of C₂H₂ in Ar/C₂H₂/H₂ mixture and (c), (d) 0.2% of CH₄ in Ar/CH₄/H₂ mixture. The substrate temperature was 610 °C for (a) and (c) and 710 °C for (b) and (d) images. The micrographs were made using Philips CM12 microscope.

CNTs deposition by plasma arcs/jets/torches at atmospheric pressure



H. Takikawa et al. *Physica B* 323, 277 (2002)., O. Smiljanic et al., *Chem. Phys. Lett.* 356, 189 (2002).

CNTs deposition by plasma arcs/jets/torches at atmospheric pressure

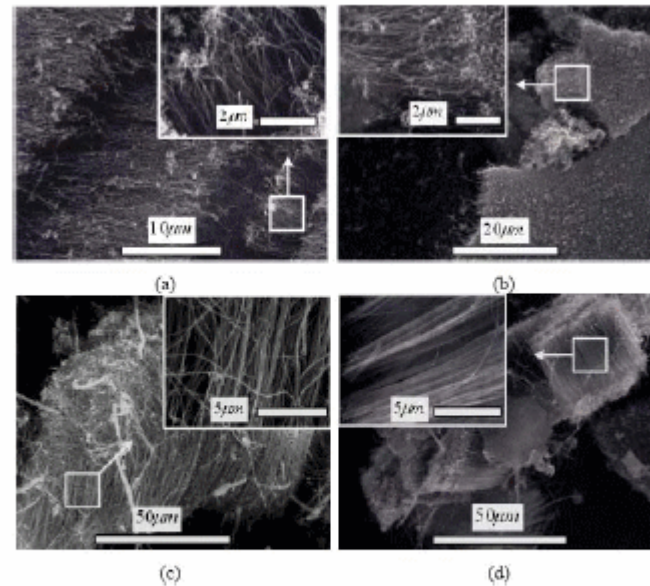
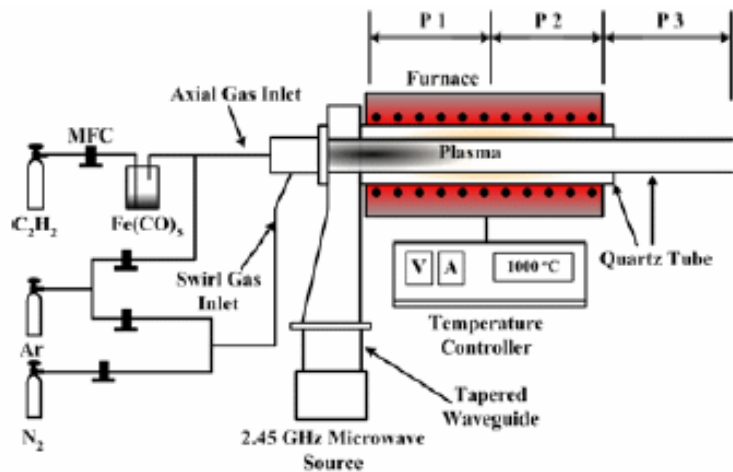
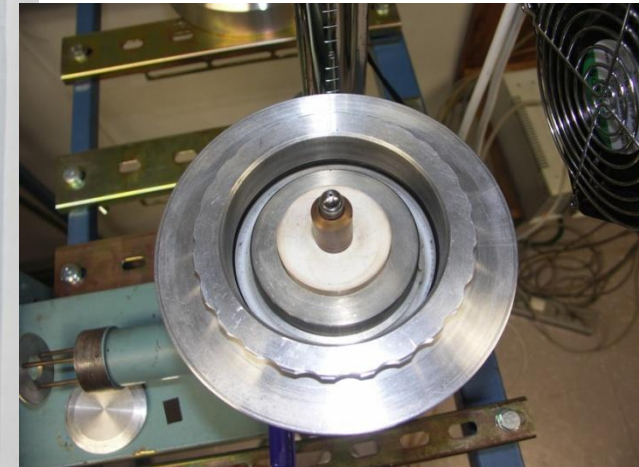
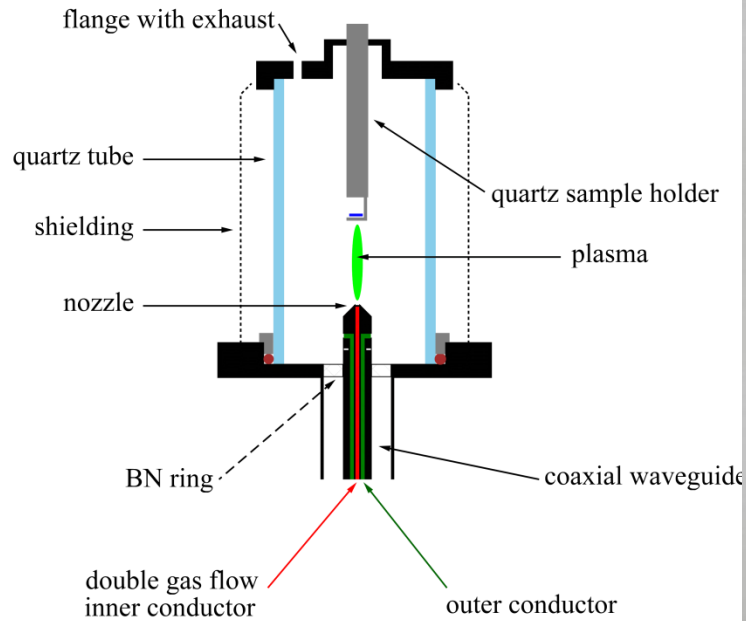
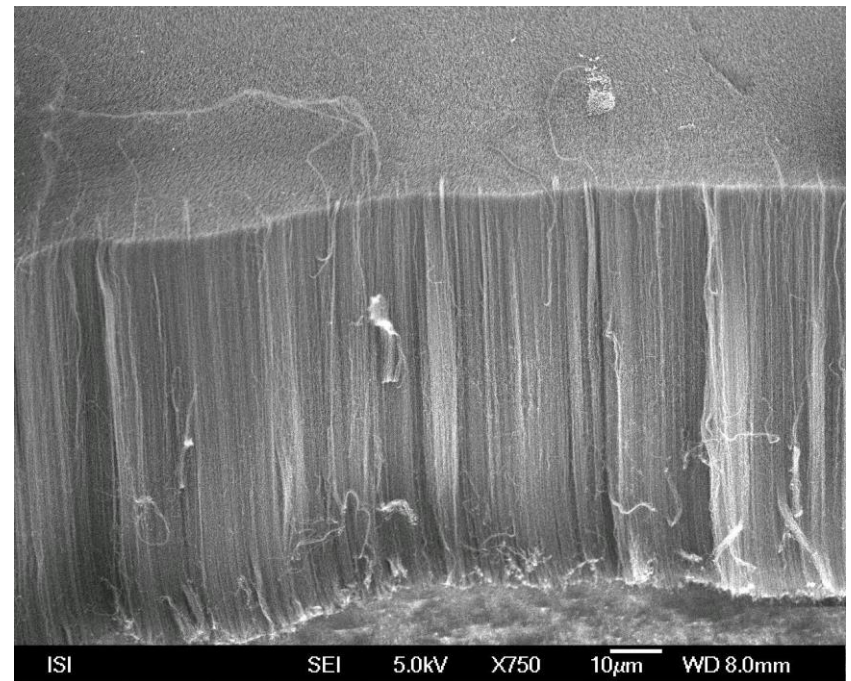
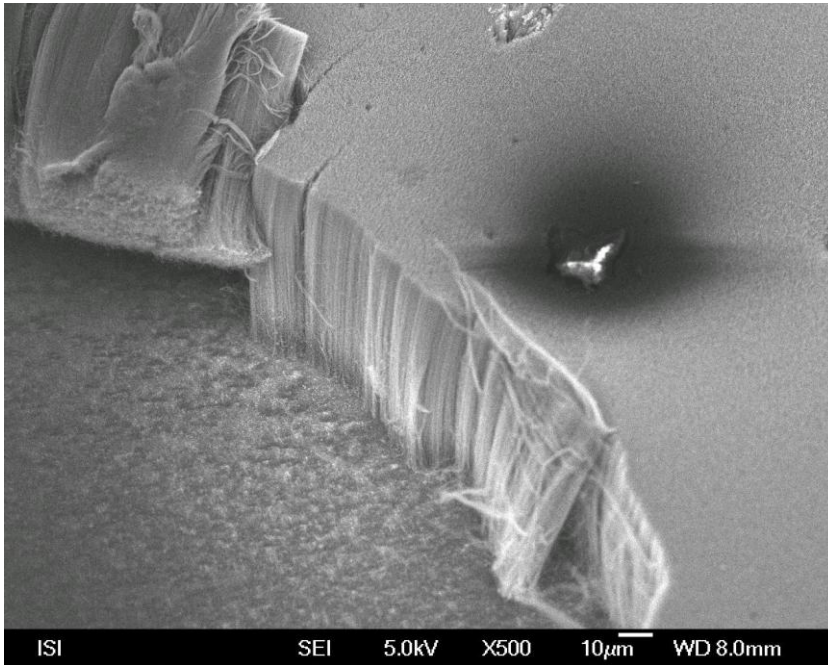


Fig. 9. SEM images of CNTs obtained from the atmospheric microwave plasma-torch. (a) at a furnace temperature of 700, (b) 800, (c) 900, and (d) 1000 °C.

CNTs synthesis by microwave plasma torch at atmospheric pressure

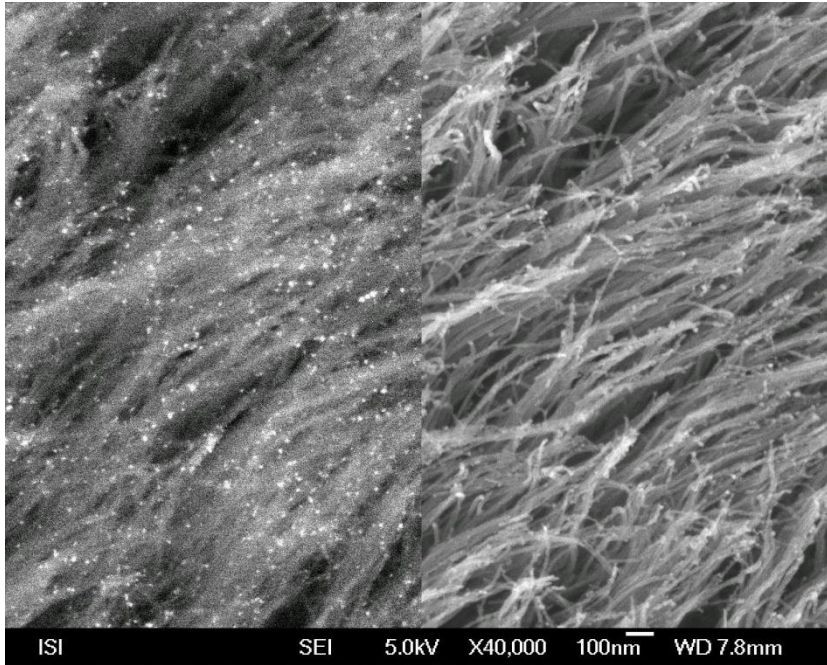


CNTs synthesis by microwave plasma torch at atmospheric pressure

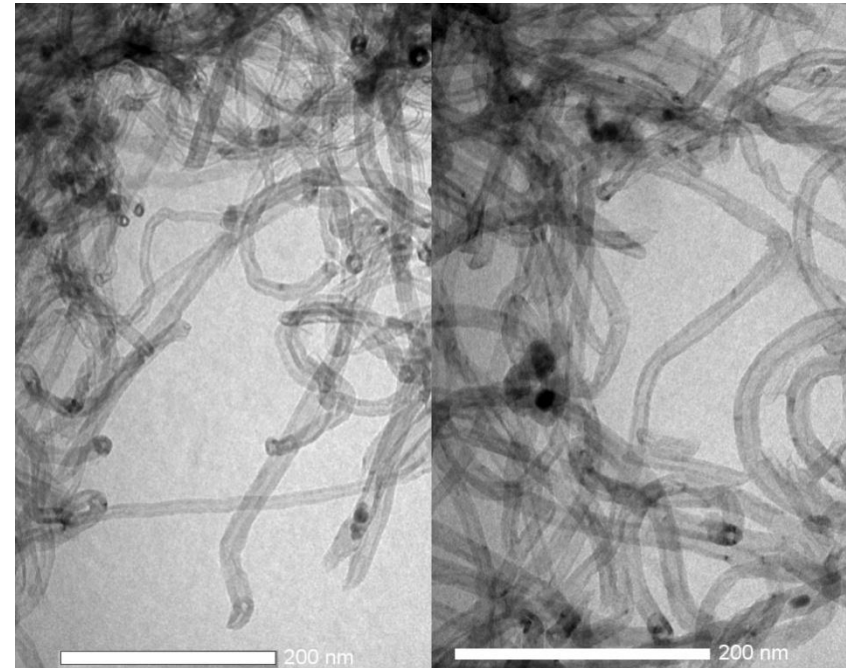


Substrate type Si/SiO₂/Fe 10 nm (Q_{CH_4} =40 sccm, Q_{H_2} =400 sccm, Ar=1500 sccm, T_S =700°C, t_d =15 min.).

CNTs synthesis by microwave plasma torch at atmospheric pressure

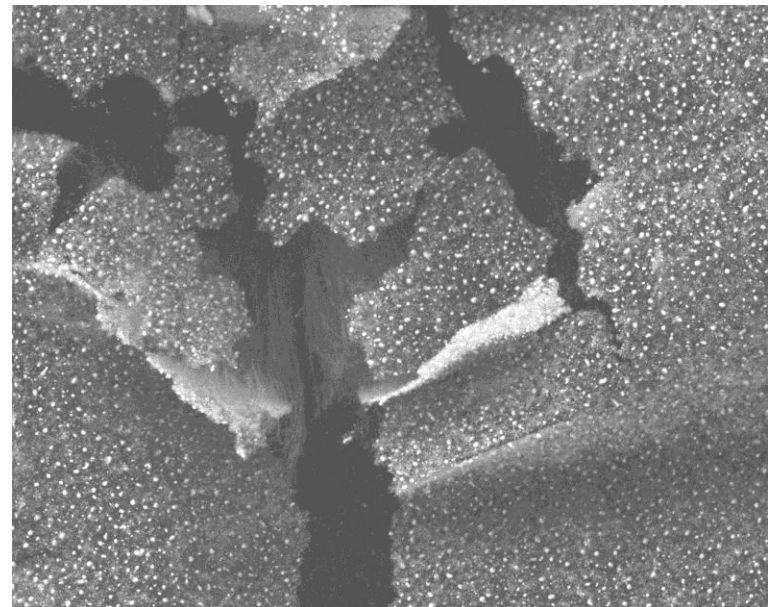
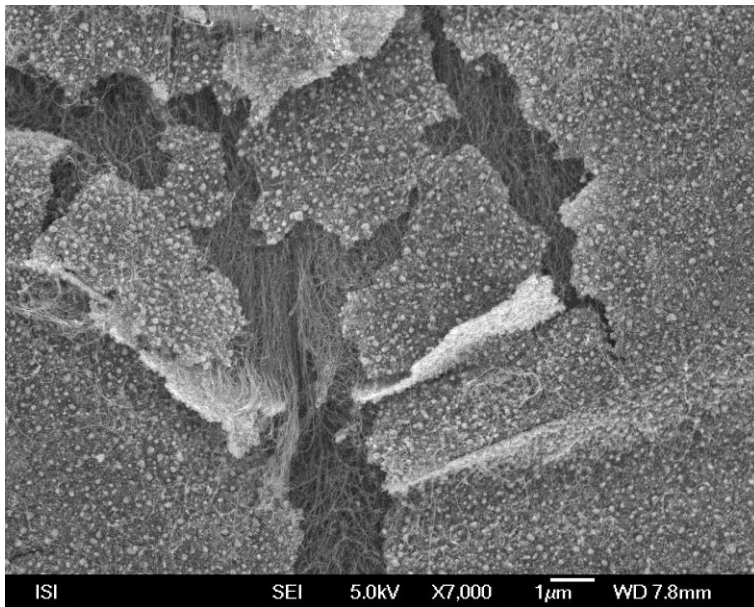


Material contrast analysis – comparison of micrographs in secondary and backscattered electrons. White points correspond to catalytic particles – tip growth mode.



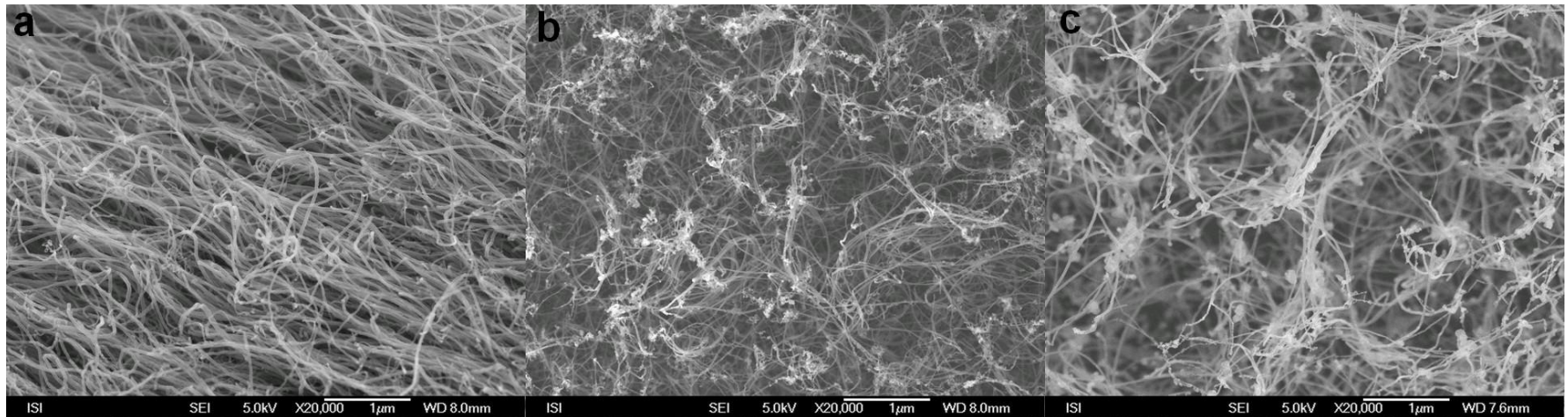
TEM micrograph

CNTs synthesis by microwave plasma torch at atmospheric pressure



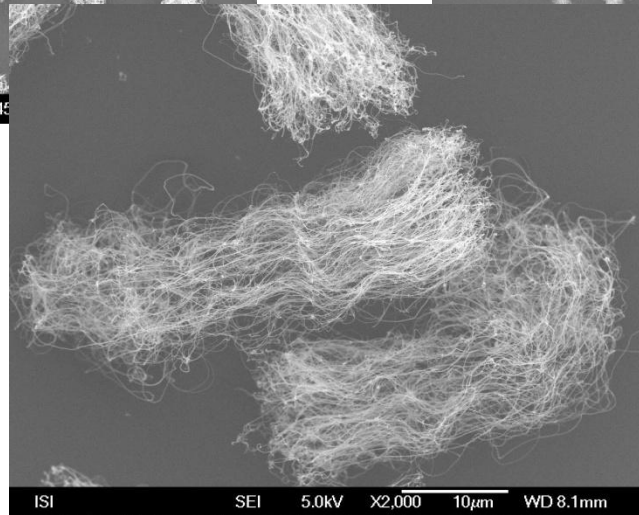
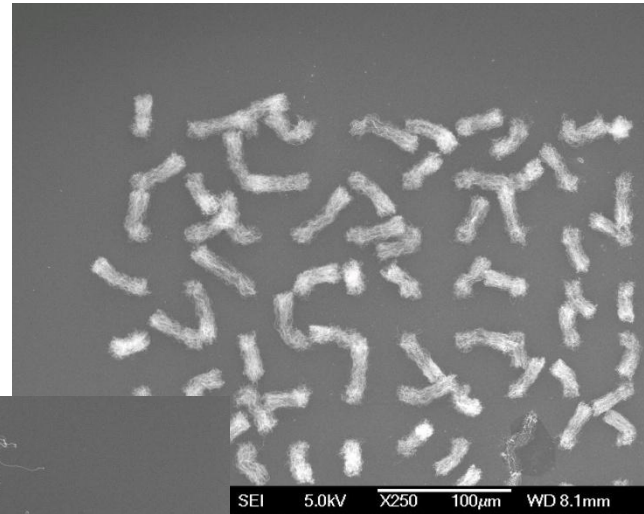
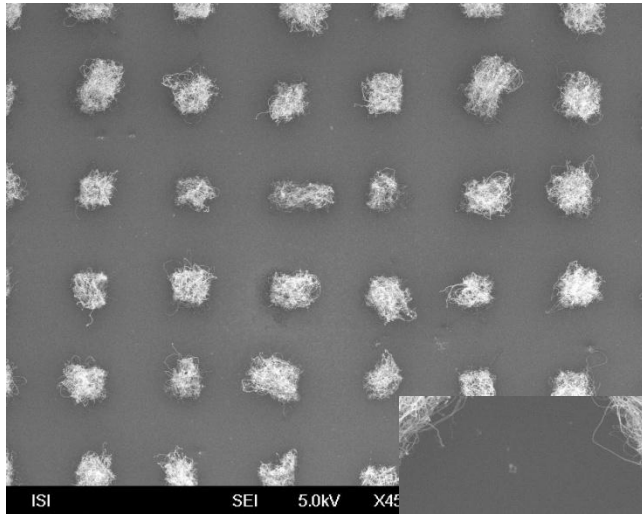
Growth termination and overlayer formation

CNTs synthesis by microwave plasma torch at atmospheric pressure



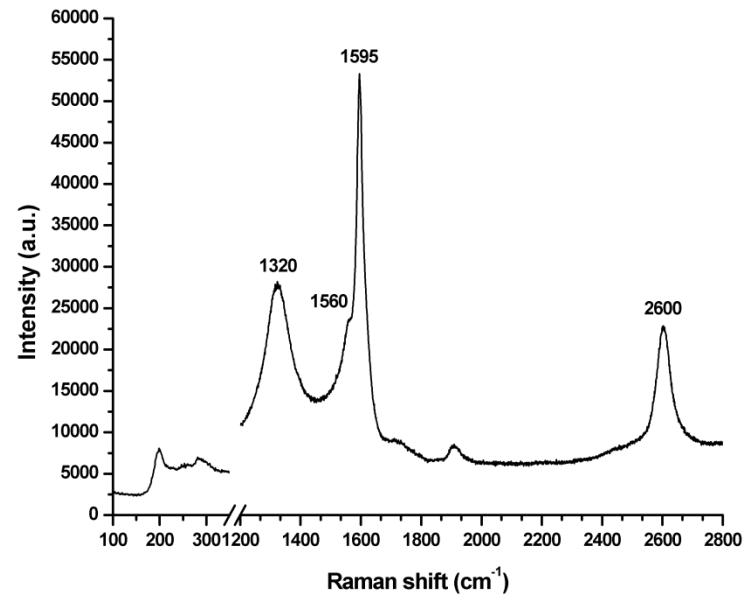
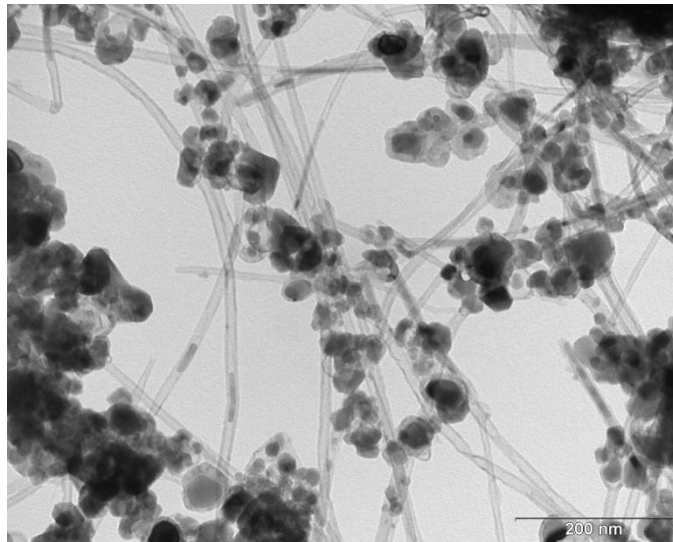
CNTs growth a) SiO_x b) Al_xO_y and c) without barrier layer.
Ar/ H_2 / CH_4 1540/430/42 sccm, 60 s, 400W, 700-750 °C

CNTs synthesis by microwave plasma torch at atmospheric pressure



Growth patterning
without barrier layer

CNTs growth in microwave plasma torch with floating catalyst

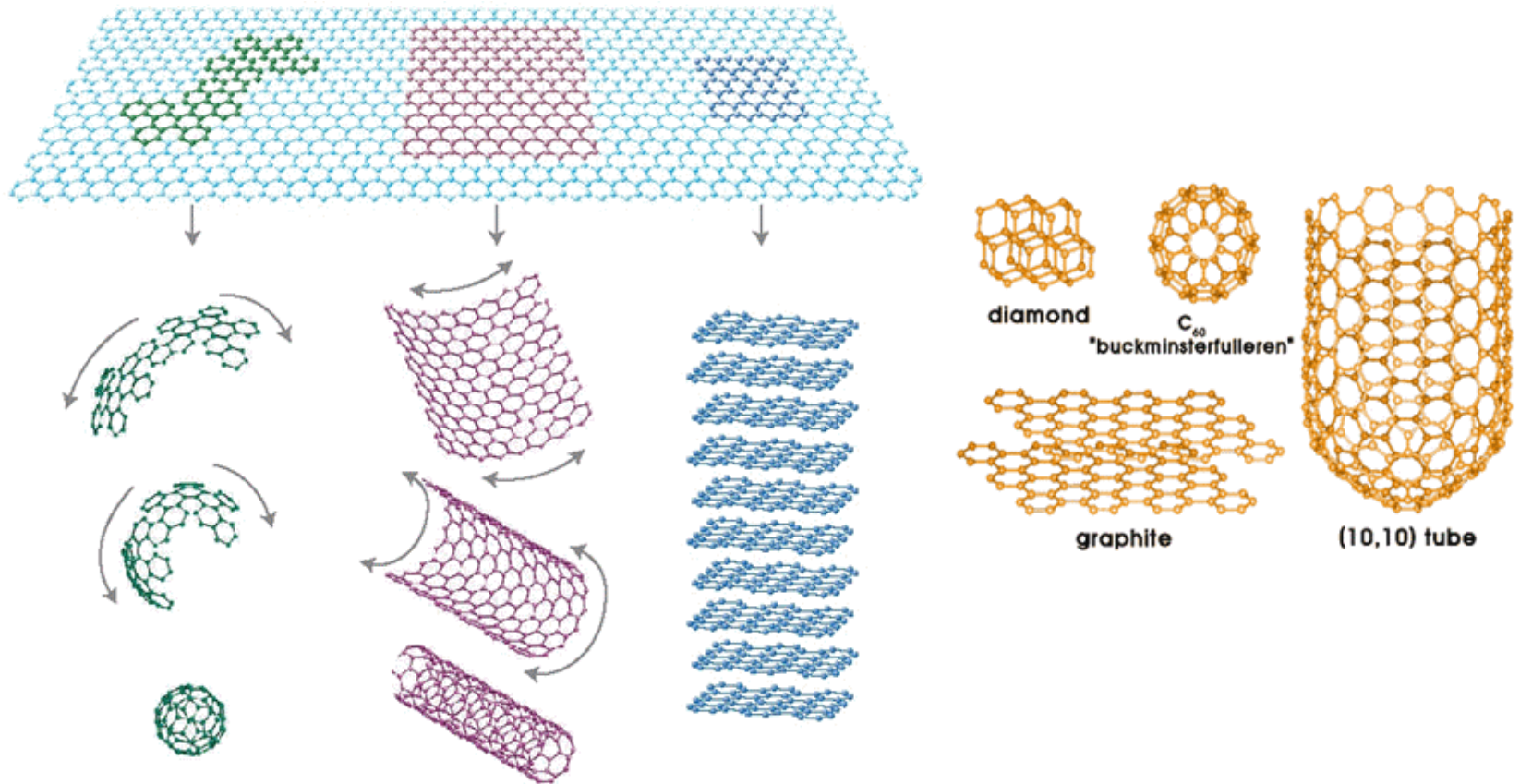


TEM micrograph of MWCNTs/SWCNTs deposited from mixture of Ar/H₂/CH₄ and Fe(CO)₅

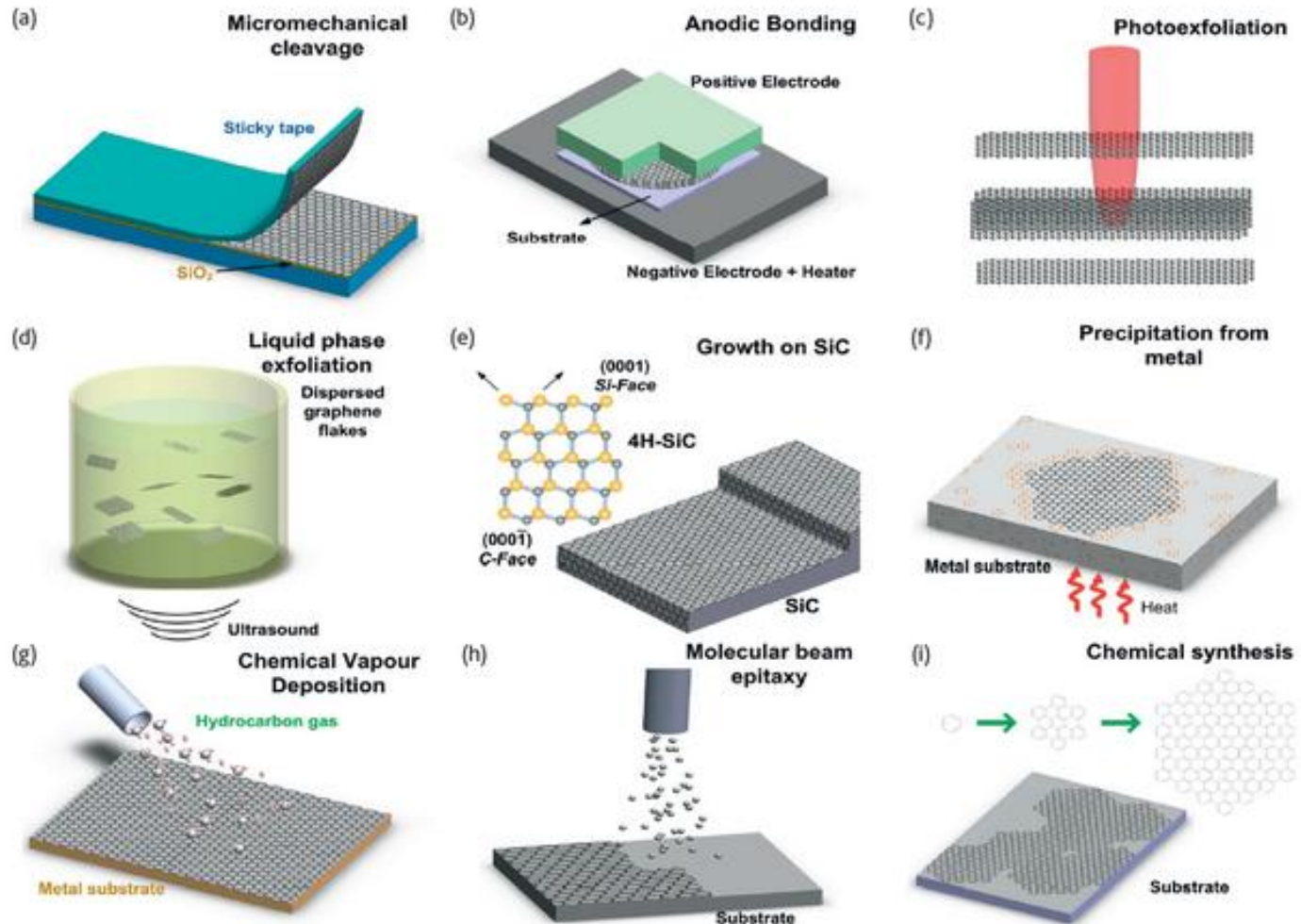
Deposition of SWCNTs on the substrate using ethanol admixture

Raman spectra of deposited nanostructures

Various forms of carbon

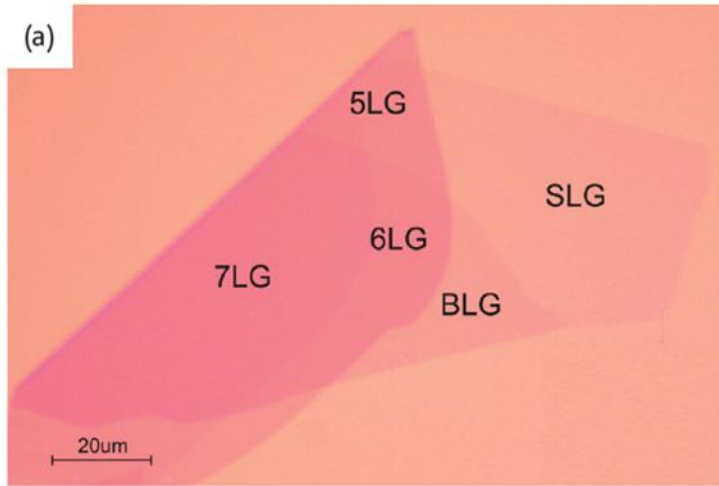


Methods of making graphene

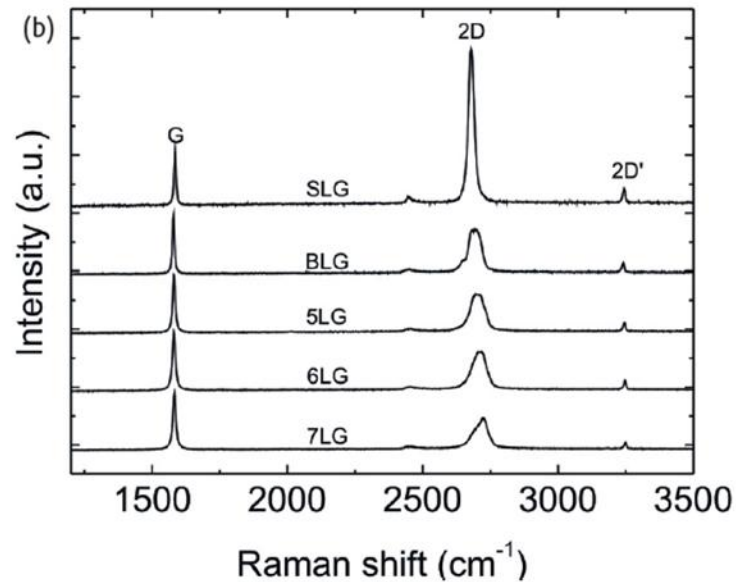


F. Bonaccorso et. al. Production and processing of graphene and 2d crystals, Materials Today 15(12), 2012, 564

Graphene identification in Raman spectra



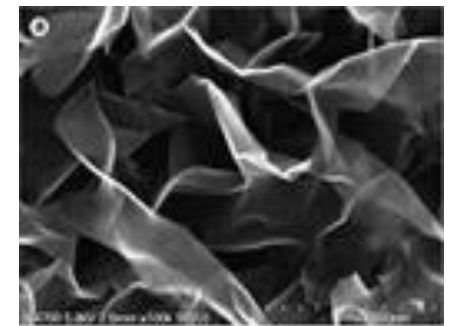
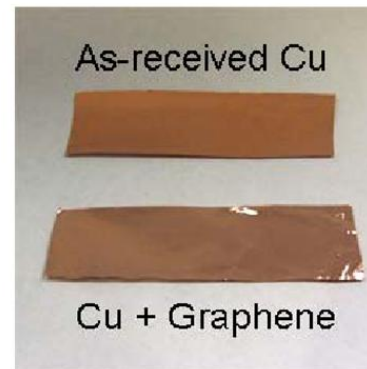
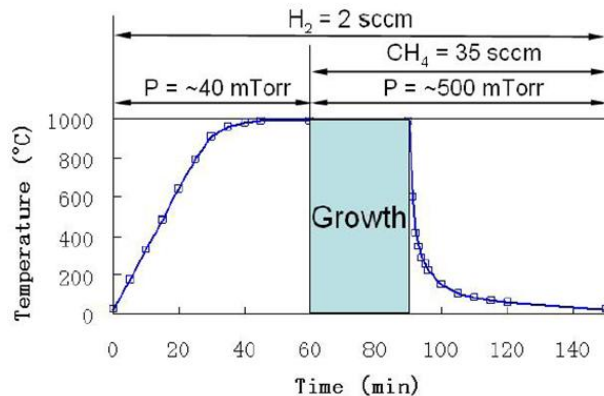
Optical contrast on SiO₂, best around 300 nm thickness.



Highly sensitive Raman signal – strong enhancement of 2D mode. No defects – no D peak around 1300 cm⁻¹.

Graphene deposition using plasma sources

- Synthesis in volume of the plasma discharge
- Synthesis of vertical aligned graphene nanosheets on substrates
- Synthesis of graphene on metallic or dielectric substrates by PECVD
- Plasma pretreatment, cleaning of the substrate, functionalization of the deposition layer – graphane (H_2), graphene transfer



Graphene deposition using plasma sources

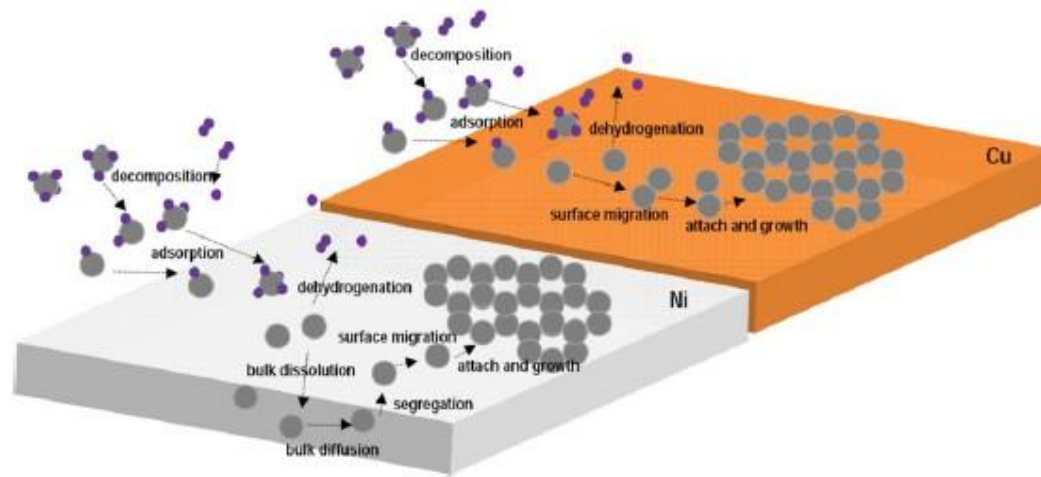


Fig. 2. Growth kinetics in CVD-produced graphene on various catalysts: Case of CH₄ on Ni and Cu.

R. Munoz and C. Gomez-Aleixandre, Review of CVD Synthesis of Graphene, Chem. Vap. Deposition 2013, 19, 297

Graphene deposition using plasma sources

Low pressure microwave plasma surface wave discharge.

Cu (30 μm), Al (12 μm), Ni foils pretreated in Ar/H₂ plasma at 5 Pa for 20 minutes. Deposition parameters: 3-4.5 kW MW power, deposition time 30-180 s in CH₄/Ar/H₂ 30/20/10 sccm mixture.

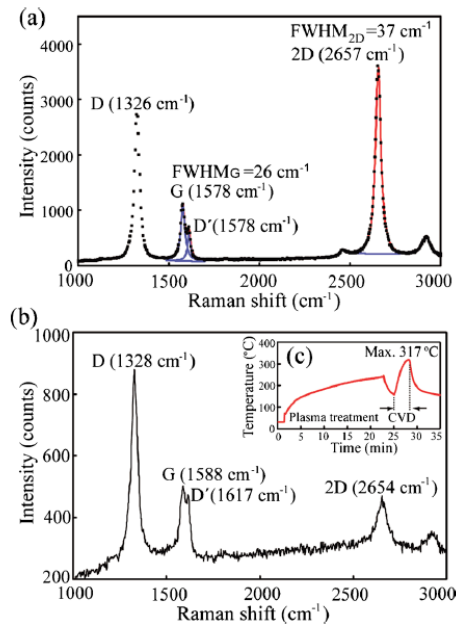


FIG. 1. (Color online) Raman spectra (638 nm laser, 1 μm spot size) of graphene-based films deposited at substrate temperatures below 400 °C by SWP-CVD. (a) Raman spectrum of a typical graphene-based film deposited on Cu foil (CVD conditions: 5 Pa, CH₄/Ar/H₂=30/20/10 SCCM, 3 kV per a MW generator, 30 s). (b) Raman spectrum of a graphene-based film deposited on Al foil (CVD conditions: 3 Pa, CH₄/Ar/H₂=30/20/10 SCCM, 4 kW per a MW generator, 180 s). (c) Substrate temperature profile during the Ar/H₂ plasma treatment and the plasma CVD for the synthesis of the film on Al foil shown in Fig. 1(b).

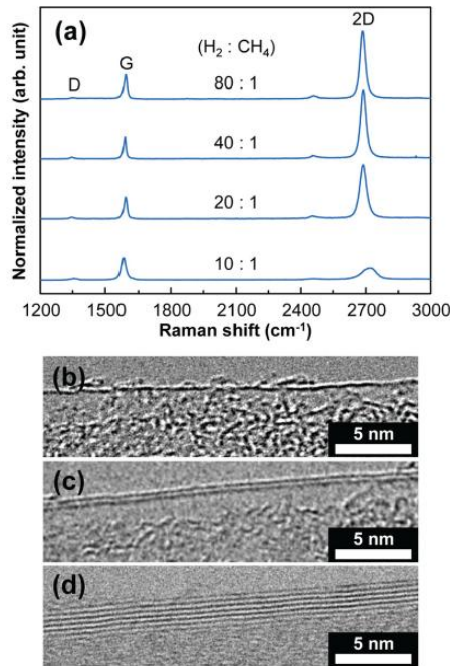


FIG. 2. (Color online) (a) Raman spectra taken at an excitation wavelength of 514 nm for the graphene films synthesized at various gas mixing ratio (synthesis time: 1 min, temperature: 750 °C). HR-TEM images of the graphene films synthesized at various gases mixing ratio: (b) 80:1 (H₂:CH₄), (c) 40:1, and (d) 10:1.

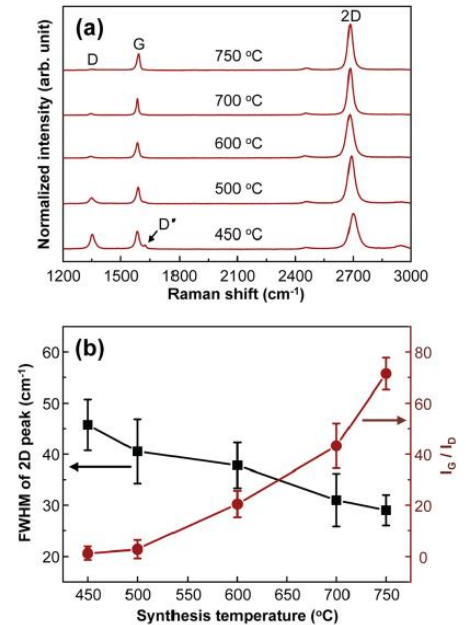


FIG. 3. (Color online) (a) Raman spectra taken at an excitation energy of 2.41 eV for the graphene synthesized at several synthesis temperatures (gas mixing ratio (H₂:CH₄): 80:1, synthesis time: 1 min). (b) FWHM of the 2D peak and the intensity ratio of the 2D peak compared to the G peak as a function of synthesis temperature.

Y. Kim et al, Low-temperature synthesis of graphene on nickel foil by microwave plasma chemical vapor deposition, APPLIED PHYSICS LETTERS 98, 263106 (2011).

J. Kim et al., Low-temperature synthesis of large-area graphene-based transparent conductive films using surface wave plasma chemical vapor deposition, APPLIED PHYSICS LETTERS 98, 091502 2011.

Graphene deposition using plasma sources

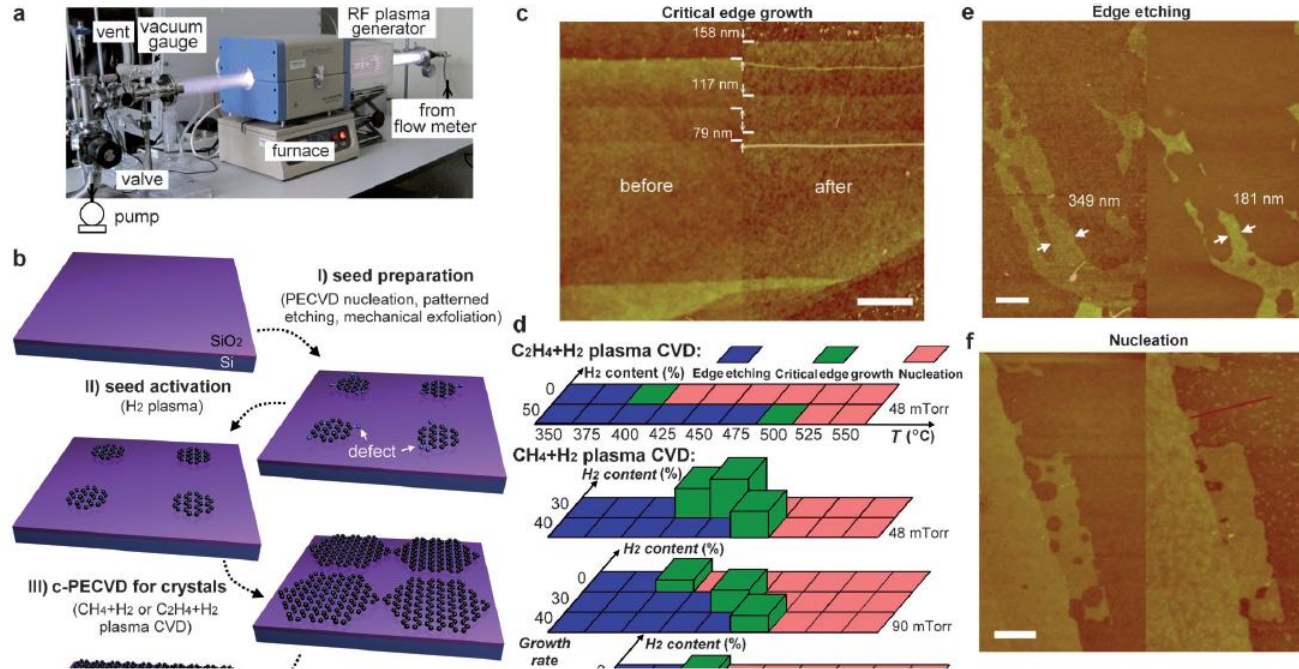


Figure 1. a) The remote radiofrequency (RF) PECVD system used. b) Schematic illustration of the c-PECVD procedure. c) AFM images of a peel-off graphene flake before (left) and after (right) c-PECVD. d) Plots of the experimental results as a function of the temperature (T) and H_2 content at 48, 90, and 300 mTorr. The blue, green, and red areas correspond to the parameters for edge etching, critical edge growth, and cluster nucleation, respectively. The height of the green columns indicates the growth rate. e, f) AFM images of peel-off graphene flakes after activation of the edges with a H_2 plasma (250 mTorr, 500°C) for 20 min (left columns), followed by $CH_4 + H_2$ plasma CVD (30% H_2 , 300 mTorr, 550°C) for 80 min (e, right column) or $CH_4 + H_2$ plasma CVD (20% H_2 , 300 mTorr, 600°C) for 40 min (f, right column). The height profile across the red line in the AFM image in (f) is shown below the AFM image. Scale bars (c,e,f): 500 nm.

RF PECVD remote plasma system with furnace and Si/SiO₂ substrate

D. Wei et al., Critical Crystal Growth of Graphene on Dielectric Substrates at Low Temperature for Electronic Devices, *Angew. Chem. Int. Ed.* 2013, 52, 14121–14126.

Graphene deposition using plasma sources

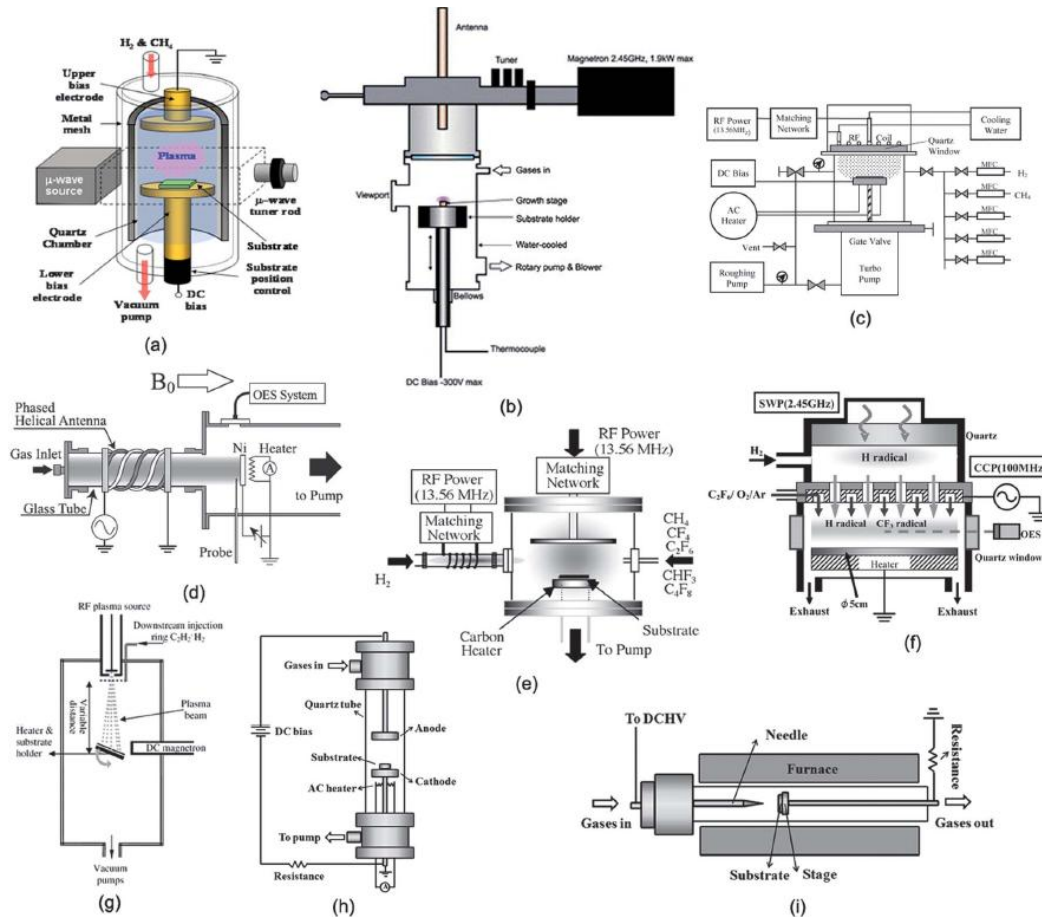


Fig. 1 Schematic diagrams of various PECVD systems for VG growth: (a) TE-MW (reprinted with permission from ref. 67; Copyright 2010 American Institute of Physics), (b) TM-MW (reprinted with permission from ref. 25; Copyright 2006 Elsevier), (c) ICP (reused with permission from ref. 68; Copyright (2004) Elsevier), (d) helicon plasma (reprinted with permission from ref. 24; Copyright 2006 Japan Society of Applied Physics), (e) CCP + ICP (reused with permission from ref. 69; Copyright 2005 Elsevier), (f) VHFCCP + MW (reprinted with permission from ref. 29; Copyright 2008 American Institute of Physics), (g) expanding CCP (reprinted with permission from ref. 70; Copyright 2010 Institute of Physics Publishing), (h) parallel-plate dc glow discharge plasma, and (i) pin-to-plate normal glow discharge plasma.

Z. Bo et al., Plasma-enhanced chemical vapor deposition synthesis of vertically oriented graphene nanosheets, *Nanoscale*, 2013, 5, 5180.

Graphene deposition using plasma sources

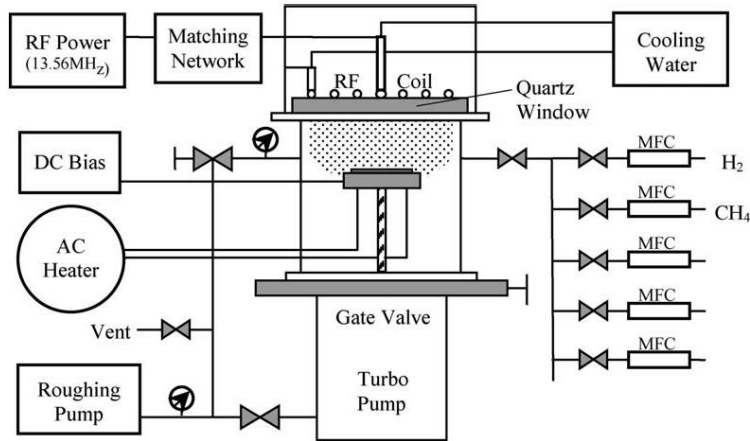
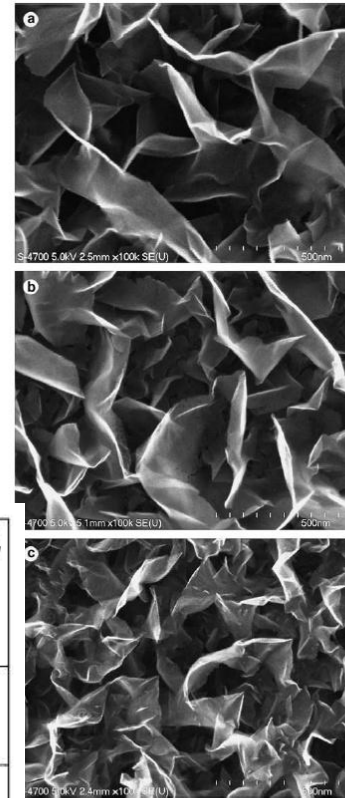
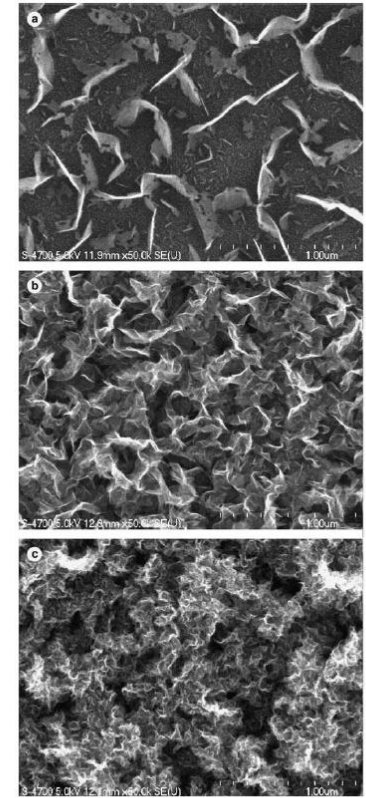


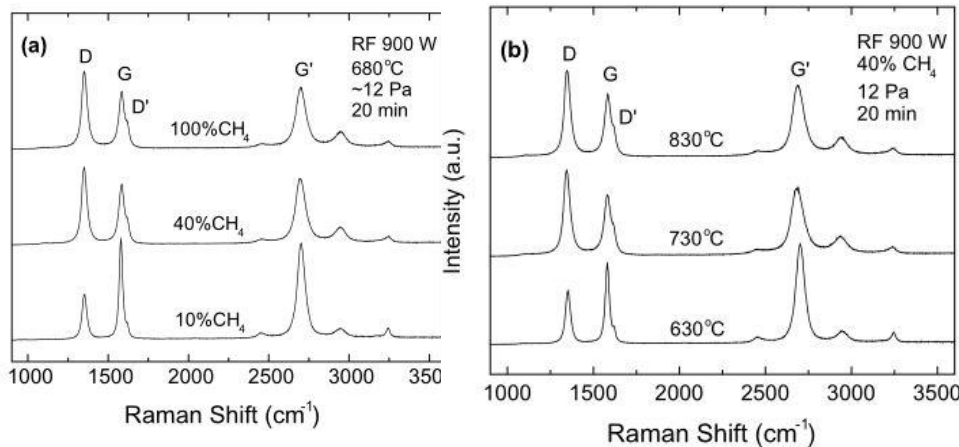
Fig. 1. Schematic of the inductively coupled RF PECVD system used for carbon nanosheet deposition



SEM images of carbon nanosheets grown at different CH₄ ratios on Si substrates: (a) 10% CH₄; (b) 40% CH₄; (c) 100% CH₄. Other deposition conditions are RF 900 W, 680 °C, ~12 Pa, 20 min.



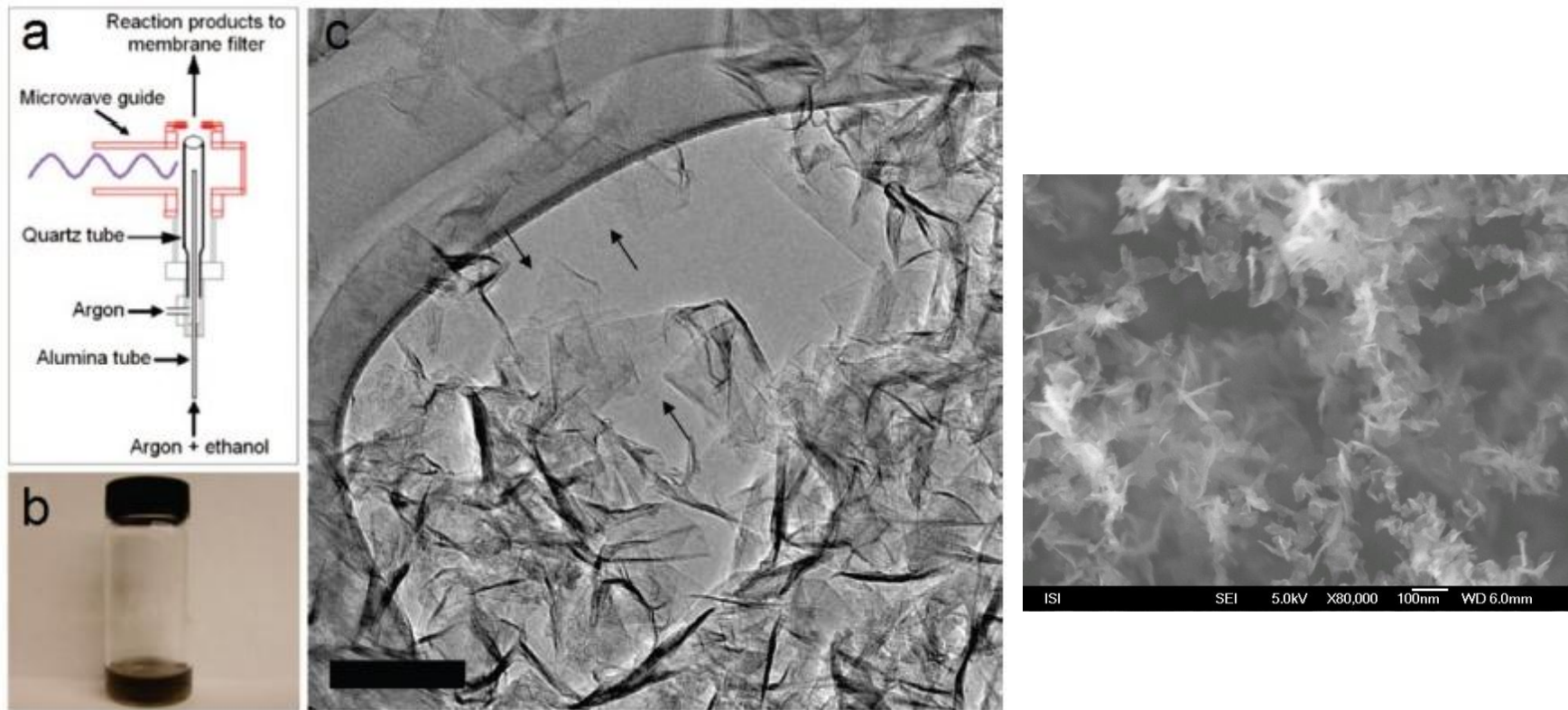
SEM images of carbon nanosheets grown at different substrate temperatures on Si substrates: (a) 630 °C; (b) 730 °C; (c) 830 °C. Other deposition conditions are RF 900 W, 40% CH₄, 12 Pa, 20 min.



J. Wang et.al. Synthesis of carbon nanosheets by inductively coupled radio-frequency plasma enhanced chemical vapor deposition, Carbon 42 (2004) 2867–2872.

RF ICP CVD 13,56 MHz 900 W, 12 Pa, H₂/CH₄ mixture . Substrate Si, SiO₂, Al₂O₃, Mo, Cu etc.

Graphene synthesis in volume at atmospheric pressure



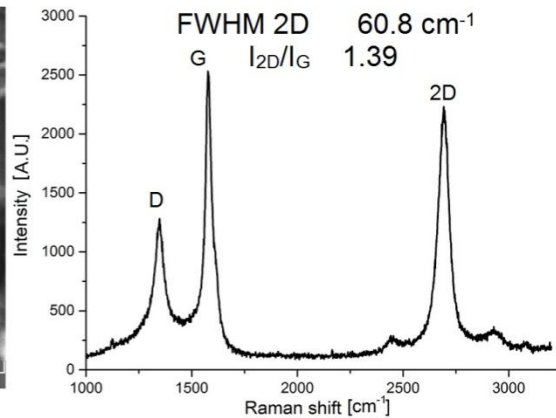
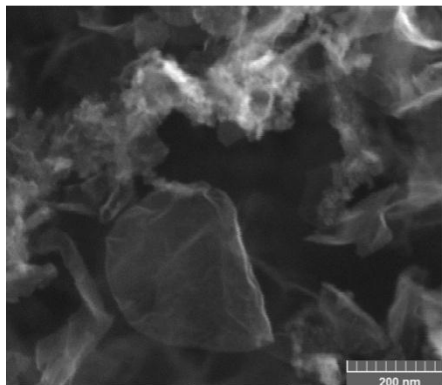
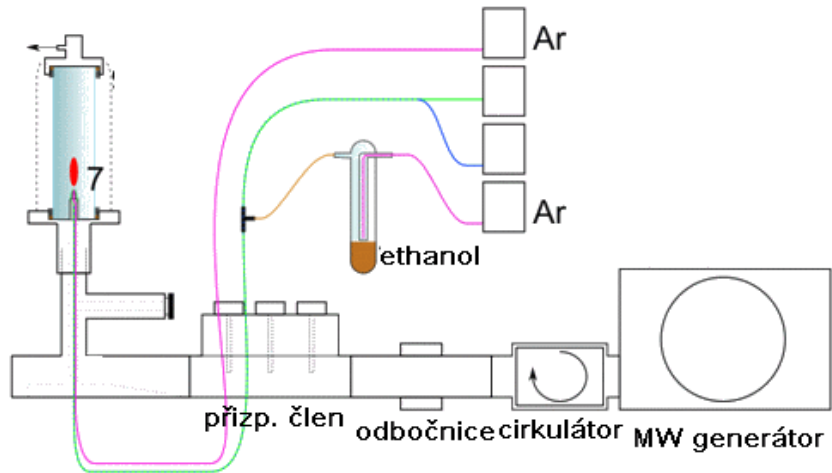
Decomposition of ethanol C_2H_5OH or dimethylether CH_3OCH_3 leads to formation of graphene sheets.

A. Dato, V. Radmilovic, Z. Lee, J. Phillips, and M. Frenklach, Substrate-Free Gas-Phase Synthesis of Graphene Sheets, *Nano Letters*, 8 (7), 2008, 2012.

A. Dato, M. Frenklach, Substrate-free microwave synthesis of graphene: experimental conditions and hydrocarbon precursors. *New Journal of Physics*, 2010, 12.12: 125013.

E. Tatarova et al. Microwave plasma based single step method for free standing graphene synthesis at atmospheric conditions. *Applied Physics Letters*, 2013, 103.13: 134101.

Graphene synthesis in volume at atmospheric pressure



Graphene nanoribbons

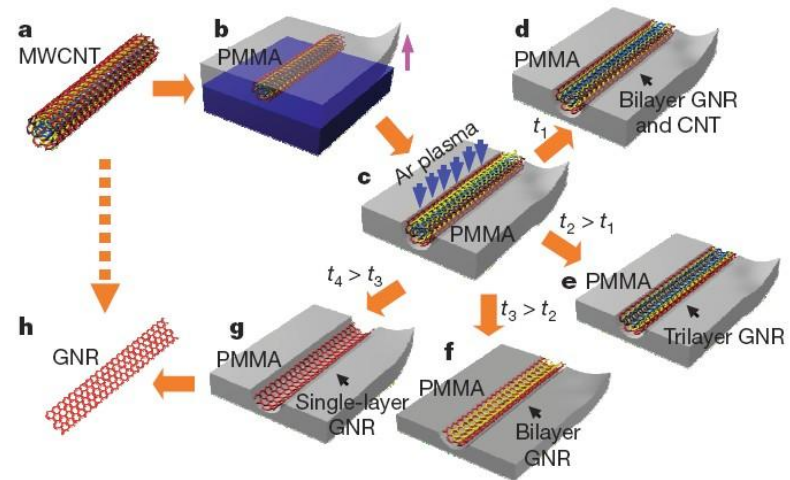
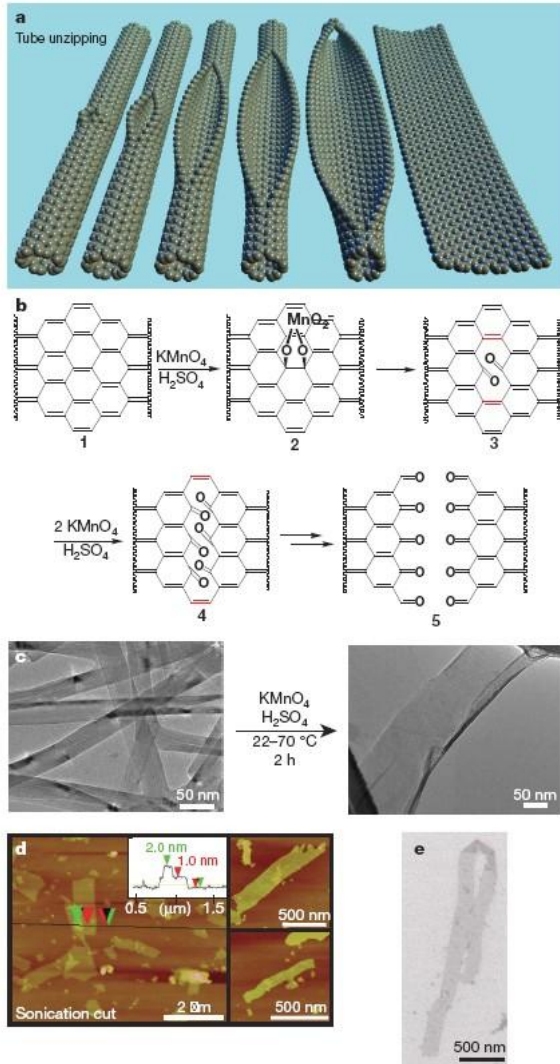


Figure 1 | Making GNRs from CNTs. **a**, A pristine MWCNT was used as the starting raw material. **b**, The MWCNT was deposited on a Si substrate and then coated with a PMMA film. **c**, The PMMA–MWCNT film was peeled from the Si substrate, turned over and then exposed to an Ar plasma. **d–g**, Several possible products were generated after etching for different times: GNRs with CNT cores were obtained after etching for a short time t_1 (**d**); tri-, bi- and single-layer GNRs were produced after etching for times t_2 , t_3 and t_4 , respectively ($t_4 > t_3 > t_2 > t_1$; **e–g**). **h**, The PMMA was removed to release the GNR.

Liyang Jiao et al., Narrow graphene nanoribbons from carbon nanotubes, 458, Nature, 877.

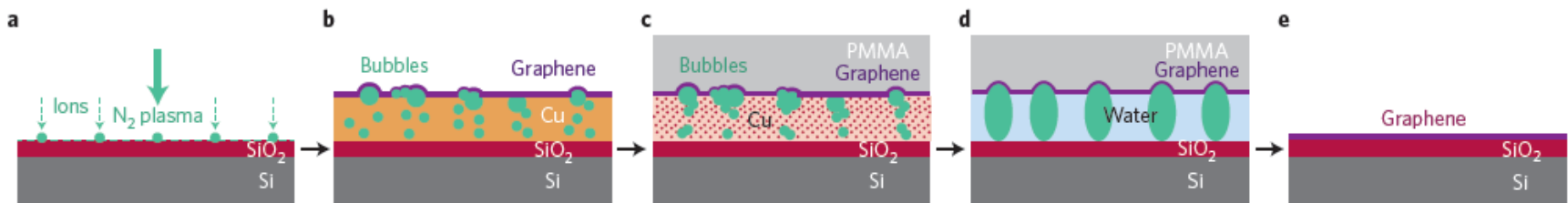
Dmitry V. Kosynkin et al., Longitudinal unzipping of carbon nanotubes to form graphene nanoribbons, Nature, 458, 2009, 872.

P. Ruffieux et al., On-surface synthesis of graphene nanoribbons with zigzag edge topology, Nature, 531, 2016, 489.

GNR – zig-zag metallic, armchair – metallic and semiconducting

Graphene transfer to dielectric substrate

- Graphene transfer scheme on Cu foil: a) PMMA mask b) etching of graphene on one side of the foil in O₂ plasma, c) chemical etching of Cu (for example in FeCl₃) d) transfer of PMMA+graphene to dielectric substrate e) chemical or plasma etching of PMMA.
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- Commercial presentations: AIXTRON Black Magic, Oxford Nanofab